



## Material Content Data Sheet



<b>Sales Product Name</b>		IPS65R1K4C6		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001081510						
<b>Package</b>		PG-TO251-3-342		<b>Weight*</b>		317.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.898	0.60	0.60	5968	5968
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.26	46.32	462666	463268
	non noble metal	aluminium	7429-90-5	0.488	0.15	0.15	1535	1535
wire	non noble metal	aluminium	7429-90-5	0.488	0.15	0.15	1535	1535
encapsulation	organic material	carbon black	1333-86-4	1.418	0.45		4459	
	plastics	epoxy resin	-	24.811	7.80		78039	
	inorganic material	silicondioxide	60676-86-0	115.549	36.34	44.59	363441	445939
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11764	11764
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4468	4479
solder	non noble metal	tin	7440-31-5	0.042	0.01		133	
	noble metal	silver	7440-22-4	0.053	0.02		166	
	non noble metal	lead	7439-92-1	2.019	0.64	0.67	6350	6649
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60320	60398
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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